NATIONAL RADIO ASTRONOMY OBSERVATORY CHARLOTTESVILLE, VIRGINIA

ELECTRONICS DIVISION INTERNAL REPORT No. 278

DESIGN AND PERFORMANCE OF CRYOGENICALLY-COOLED, 14.4-15.4 GHz HEMT AMPLIFIER

M. W. POSPIESZALSKI AND W. LAKATOSH

August 1988

NUMBER OF COPIES: 250

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M. W. Pospieszalski and W. Lakatosh

I. Introduction

This report covers the design and performance of cryogenically-cooled, 14.4-15.4 GHz amplifiers built with commercially-available FHROIFH (Fujitsu) HEMT's. The design was computer optimized for gain and noise performance in a manner similar to previously described X-band designs [1], [2], although a different topology of an input matching network was assumed. A commercially-available Fujitsu HEMT, FHROIFH, was used. The signal and noise model of this transistor was extensively discussed in [3]. The typical parameters measured at the cold input of the amplifier were: minimum noise temperature at midband $T_{min} = 17$ K, average noise temperature over 1 GHz bandwidth $T_{nav} = 19$ K and gain $G_T = 30$ dB ± 2 dB over the same bandwidth. The noise temperature is by a factor of two better in the band center and by a factor of three better at the band edges than for the previous NRAO design [4]. This can be mostly attributed to the use of a much better device (HEMT instead of a FET), but also to a different design approach.

II. Amplifier Design and Realization

Photographs of a finished amplifier are shown in Figure 1. Many design features are similar to the previously described designs [1], [2]. A most notable difference is a topology of an input matching network which consists of (starting at the generator side): a parallel high impedance open-circuited stub, a length of 50 Ω air slab line and length of low impedance slab line (partially filled with teflon). The input and first interstage matching networks were computer optimized to yield minimum average noise in 14.4-15.4 GHz band at 12.5 K ambient temperature, while the interstage coupling network and output network were optimized for gain flatness.

The details of the d.c. separation circuit and bias circuit and their microwave and low frequency equivalent circuits are shown in Figure 2. The comparison between computer predicted and measured performance of the three-stage amplifier (U-5) at room and cryogenic temperature is shown in Figure 3. The experimental data of Figure 3 are taken for all transistors biased at $V_{ds} = 2 V$, $I_{ds} = 10 \text{ mA}$ and $V_{ds} = 2 V$, $I_{ds} = 5 \text{ mA}$ for room and cryogenic temperatures, respectively. The cryogenic measurement was done with all HEMT's illuminated. The computed data are for the circuit description as given in Figures 1 and 2, using the signal and noise model of the FHR01FH HEMT developed in [3]. The input and output return loss measured at room temperature is compared with the model prediction in Figure 4.

The amplifier characteristics were found to be very sensitive to the electrical length of the open-circuited stub. This is because the length of this stub becomes quarter-wave at the frequency of 17.5 GHz. The stub is realized by placing a tinned copper wire of 10 mills in diameter in a channel milled in the amplifier housing (compare Figure 1). The end of the stub rests in a movable rexolite support, which provides at the same time the mechanical stability and required fine tuning.

III. Summary of Performance of K₁₁-Band Amplifiers

The summary of cryogenic performance of eight K_u -band amplifiers is given in Table I. Full noise and gain characteristics of six of those amplifiers are shown in Figure 5. For most of the amplifiers, the only required tuning procedure was an adjustment of electrical length of the parallel stub by movement of its rexolite support. Indeed, the repeatability of amplifier characteristics was quite good. All the amplifiers were built with FHRO1FH HEMT's from lot #C923. The spread in minimum noise temperature at midband was less than 3.5 K for seven amplifiers. This is consistent with the repeatability of noise performance of Fujitsu HEMT's with good pinch-off characteristics, as observed in X-band amplifiers (\pm 1.5 K) [3], [5], and also with estimated accuracy of measurement (\pm 2 K in K_u-band).

IV. Conclusions

The design, construction and performance of cryogenically-cooled, 14.4-15.4 GHz HEMT amplifiers were described. The cryogenic noise performance of these amplifiers is believed to be the best yet reported at this frequency.

V. References

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- [4] S. Weinreb and R. Harris, "Low-Noise, 15 GHz, Cooled, GaAsFET Amplifier," NRAO Electronics Division Internal Report No. 235, September 1983.
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	Noise Temp. ¹ [K]		Gain ² [K]	
Amplifier	Minimum	Average	Minimum	Maximum
U-13	20.5	22.8	25.3	29.1
U-2 ³	18.3	22.5	27.2	29.3
U-3	18.2	21.1	28.2	32.1
U-4	18.3	20.0	28.3	31.0
U-5	16.2	18.1	28.7	32.1
U-6	17.4	20.2	27.8	30.6
U- 7	15.0	16.0	28.6	30.4
U-8	15.6	19.1	28.1	31.6

TABLE I.The Summary of Cryogenic Performanceof the 14.4-15.4 GHz Amplifiers

¹Referred to the cold input of an amplifier.

²Includes a cold isolator and dewar transition at the output side.

³Prototypes.





Fig. 1. Three-stage 14.4-15.4 GHz amplifier with cover plate removed.



Fig. 2. (A) Schematic view of the realization of the d.c. separation circuit. (B) Cross-section of the reentrant line after assembly.
(C) High frequency equivalent circuit of the bias and d.c. separation circuits. (D) Schematic of the bias circuit. Element values are given in ohms, picofarads, nanohenries, and inches.



Fig. 3. Comparison between model prediction and measured performance of three-stage, K_u -band, FHRO1FH amplifier (U-5) at 297 K and 12.5 K. At room temperature all transistors are biased at $V_{ds} = 2 V$, $I_{ds} = 10 mA$. At cryogenic temperature all transistors are biased at $V_{ds} = 2 V$, $I_{ds} = 2 V$, $I_{ds} = 5 mA$.



Fig. 4. Comparison between model prediction and measured return loss of the three-stage, K_u -band, FHR01FH amplifier (U-5) at 297 K. All transistors are biased at $V_{ds} = 2$ V, $I_{ds} = 10$ mA.



Fig. 5. Cryogenic performance of six K_u -band amplifiers under optimal bias conditions. The noise temperature is referred to cold input of an amplifier. The measured gain characteristics include the contribution of the cold isolator at the output and the dewar transition (about 1 dB of loss).

APPENDICES

Appendix I.	Part	s List for K _u -Band HEMT Amp (14.4-15.4 GHz)
Appendix II.	Draw	ings
	A.	Amplifier Alignment Procedure
	B.	Stub Dielectric Support
	C.	Chassis
	D.	Amplifier Cover
	E.	Transistor Strap
	F.	Output End Plate
	G.	Input End Plate
	H.	Coaxial Transformer
	I.	Support Inner Conductor
	J.	Interstage Inner Conductor

- K. Output SMA Modified
- L. Input SMA Modified

ITEM	QUANTITY	REF. DESIG.	DESCRIPTION	MFG.	PART NUMBER
1	1		Amplifier alignment procedure	NRAO	C53208M017
2	1		Stub dielectric support	NRAO	A53208M020
3	1		Chassis	NRAO	C53208M009, Rev. C
4	1		Amplifier cover	NRAO	B53208M010
5	6		Transistor strap	NRAO	A53208M011, Rev. A
6	1		Output end plate	NRAO	A53206M072, Rev. D
7	1		Input end plate	NRAO	A53206M071, Rev. D
8	1 ea.		Coaxial transformer	NRAO	A53208M016
9	2		Support inner conductor	NRAO	A53208M012, Rev. A
10	2		Innerstage inner conductor	NRAO	A53208M013, Rev. B
11	1		Output SMA modified	NRAO	A53208M015, Rev. A
12	1		Input SMA modified	NRAO	A53208M014, Rev. A
13	1		Power connector	Omni-Spectra	ER-7S-6
14	3		НЕМТ	Fujitsu	FHR01FH
15	6		HEMT bias leads, #36 AWG Beldsol	Belden	8058
16	6		Bias wires, #30 AWG Beldsol	Belden	8055
17	1		LED, bias wire, #30 AWG	Alpha	1851

ITEM	QUANTITY	REF. DESIG.	DESCRIPTION	MFG.	PART NUMBER
18	6		0.08x3/16 filister hd. screws, gold-plated		
19	2		2-56 x 1/2" socket head SS screws	All-Metal	
20	2		2-56 x 3/8" socket head SS screws	All-Metal	
21	4		2-56 x 3/16" socket head SS screws	All-Metal	
22	4		2-56 x 1/4" socket head SS screws		
23	12		4-40 x 1/4" socket head SS screws	All-Metal	
24	1		4-40 x 3/8" socket head SS screw	All-Metal	
25	1		4-40 x 1/2" socket head SS screws	All-Metal	
26	6		.3 pF chip capacitors	ATC	100-A-OR3-B-P-150
27	6		16 pF chip capacitors	ATC	100-A-160-K-P-50
28	6		680 pF chip capacitors	ATC	100-B-681-M-P-50
29	9		50 ohm chip resistors	Mini-Systems	WA13PG-500-J-S
30	3		10 ohm 1/8 W metal film resistor	Corning	RLR05C-10R0-FS
31	3		1000 ohm 1/8 W metal film resistor	Corning	RLR05C-1001-FS
32	3		Diode Zener	Motorola	IN4099
33	6		LED	Litronix	RL-50
34			Solder, 2% silver	Ersin	SN-62028

ITEM	QUANTITY	REF. DESIG.	DESCRIPTION	MFG.	PART NUMBER
35			Flux, rosin liquid	Lester	#1544
36			Mylar tape	Scotch	RT-56
37			Input stub, #30 AWG	Belden	8025



Appendix II.A

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Appendix II.C



Appendix II_D



Appendix II.E

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Appendix II.G





Appendix II.I



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Appendix II.J



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Appendix II.K



Appendix II.L